PATENT

I hereby certify that on the date specified below, this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

October 12, 2006 — Date

Alexandra Beggs — Alexandra Beggs

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant	: Nathan R. Brown	Attorney Docket No.	: 500200.05
Patent No.	: US 6,852,017 B2	Serial No.	: 09/910,638
Issue Date	: February 8, 2005	Filed	: July 20, 2001
Title	: METHOD AND APPARATUS FOR CHEMICAL-MECHANICAL PLANARIZATION OF MICROELECTRONIC SUBSTRATES WITH A CARRIER AND MEMBRANE		

REQUEST FOR CERTIFICATE OF CORRECTION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

A Certificate of Correction under 35 U.S.C. § 254 is respectfully requested for the above-identified patent in order to correct Patent and Trademark Office errors made during the printing of the patent. The changes in the patent needed to correct the errors are as follows:

Column, Line	Reads	Should Read
Item (56), U.S. Patent Documents	[Omitted references]	--6,290,572 B1 9/2001 Hofmann.....451/5 5,769,699 6/1998 Yu.....451/528 6,135,858 10/2000 Takahashi.....451/41--
Column 3, Line 57	"the thicket portion"	--the thicker portion--
Column 8, Line 66	[Omitted	--5. A method for removing material from a

claims] microelectronic substrate, comprising:

providing a substrate holder that carries the microelectronic substrate and at least one membrane having a first membrane portion and a second membrane portion, the at least one membrane disposed between the substrate holder and the microelectronic substrate;

engaging the microelectronic substrate with a planarizing medium;

moving at least one of a first part of the microelectronic substrate and the planarizing medium relative to the other at a first rate;

moving at least one of a second part of the microelectronic substrate and the planarizing medium relative to the other at a second rate less than the first rate; and

removing material from the first and second parts of the microelectronic substrate at approximately equal rates by biasing the first part of the microelectronic substrate against the planarizing medium with the first membrane portion having a first thickness and biasing the second part of the microelectronic substrate against the planarizing medium with the second membrane portion having a second thickness greater than the first thickness.

6. The method of claim **5** wherein engaging the microelectronic substrate with the planarizing medium includes engaging the microelectronic substrate with a polishing pad.

7. The method of claim **5** wherein moving at least one of the first part of the microelectronic substrate and the planarizing medium includes moving at least one of a first annular part of the microelectronic substrate and the planarizing medium, further wherein moving at least one of the second part of the

microelectronic substrate and the planarizing medium includes moving at least one of the planarizing medium and a second annular part of the microelectronic substrate positioned radially inwardly from the first annular part of the microelectronic substrate.

8. The method of claim **5** wherein the at least one membrane has a first surface facing toward the microelectronic substrate and a second surface facing generally opposite the first surface, further wherein biasing the microelectronic substrate against the planarizing medium includes biasing a generally flat support member against the second surface of the membrane.

9. The method of claim **5** wherein biasing the microelectronic substrate against a planarizing medium includes biasing the microelectronic substrate against a first portion of a polishing pad, further wherein moving at least one of the microelectronic substrate and the planarizing medium includes advancing the polishing pad from a supply roller to a take-up roller to engage a second portion of the polishing pad with the first and second parts of the microelectronic substrate.--

The above errors for which correction is requested under 35 U.S.C. § 254 were made in the printing of the patent . The errors are considered sufficiently important to justify the processing of a Certificate of Correction under 35 U.S.C. § 254. A Form PTO-1050, in duplicate, is enclosed herewith.

Favorable consideration of this Request is respectfully requested.

Respectfully submitted,

Date: Oct. 10, 2006

By: Edward W. Bulchis

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EWB:tdp

Enclosures:
Postcard
Form PTO-1050 (+ copy)

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UNITED STATES PATENT AND TRADEMARK OFFICE

CERTIFICATE OF CORRECTION

PATENT NO. : US 6,852,017 B2
DATED : February 8, 2005
INVENTOR(S) : Nathan R. Brown

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Column 3, Line 57	"the thicket portion"	--the thicker portion--
Column 8, Line 66	[Omitted claims]	--5. A method for removing material from a microelectronic substrate, comprising: providing a substrate holder that carries the microelectronic substrate and at least one membrane having a first membrane portion and a second membrane portion, the at least one membrane disposed between the substrate holder and the microelectronic substrate; engaging the microelectronic substrate with a planarizing medium; moving at least one of a first part of the microelectronic substrate and the planarizing medium relative to the other at a first rate; moving at least one of a second part of the microelectronic substrate and the planarizing medium relative to the other at a second rate less than the first rate; and removing material from the first and second parts of the microelectronic

substrate at approximately equal rates by biasing the first part of the microelectronic substrate against the planarizing medium with the first membrane portion having a first thickness and biasing the second part of the microelectronic substrate against the planarizing medium with the second membrane portion having a second thickness greater than the first thickness.

6. The method of claim **5** wherein engaging the microelectronic substrate with the planarizing medium includes engaging the microelectronic substrate with a polishing pad.

7. The method of claim **5** wherein moving at least one of the first part of the microelectronic substrate and the planarizing medium includes moving at least one of a first annular part of the microelectronic substrate and the planarizing medium, further wherein moving at least one of the second part of the microelectronic substrate and the planarizing medium includes moving at least one of the planarizing medium and a second annular part of the microelectronic substrate positioned radially inwardly from the first annular part of the microelectronic substrate.

8. The method of claim **5** wherein the at least one membrane has a first surface facing toward the microelectronic substrate and a second surface facing generally opposite the first surface, further wherein biasing the microelectronic substrate against the planarizing medium includes biasing a generally flat support member against the second surface of the membrane.

9. The method of claim **5** wherein biasing

	the microelectronic substrate against a planarizing medium includes biasing the microelectronic substrate against a first portion of a polishing pad, further wherein moving at least one of the microelectronic substrate and the planarizing medium includes advancing the polishing pad from a supply roller to a take-up roller to engage a second portion of the polishing pad with the first and second parts of the microelectronic substrate.--

MAILING ADDRESS OF SENDER:

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Patent No. US 6,852,017 B2

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FORM PTO-1050 (REV. 3-82)

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substrate at approximately equal rates by biasing the first part of the microelectronic substrate against the planarizing medium with the first membrane portion having a first thickness and biasing the second part of the microelectronic substrate against the planarizing medium with the second membrane portion having a second thickness greater than the first thickness.

6. The method of claim **5** wherein engaging the microelectronic substrate with the planarizing medium includes engaging the microelectronic substrate with a polishing pad.

7. The method of claim **5** wherein moving at least one of the first part of the microelectronic substrate and the planarizing medium includes moving at least one of a first annular part of the microelectronic substrate and the planarizing medium, further wherein moving at least one of the second part of the microelectronic substrate and the planarizing medium includes moving at least one of the planarizing medium and a second annular part of the microelectronic substrate positioned radially inwardly from the first annular part of the microelectronic substrate.

8. The method of claim **5** wherein the at least one membrane has a first surface facing toward the microelectronic substrate and a second surface facing generally opposite the first surface, further wherein biasing the microelectronic substrate against the planarizing medium includes biasing a generally flat support member against the second surface of the membrane.

9. The method of claim **5** wherein biasing

	the microelectronic substrate against a planarizing medium includes biasing the microelectronic substrate against a first portion of a polishing pad, further wherein moving at least one of the microelectronic substrate and the planarizing medium includes advancing the polishing pad from a supply roller to a take-up roller to engage a second portion of the polishing pad with the first and second parts of the microelectronic substrate.--

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OCT 18 2006

Sheet 1 of 1

FORM PTO-1449 (REV.7-80)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. 500200.05	APPLICATION NO. 09/910,638
INFORMATION DISCLOSURE STATEMENT *(Use several sheets if necessary)*		APPLICANT(S) Nathan R. Brown	
		FILING DATE July 20, 2001	GROUP ART UNIT 3729

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA	5,769,699	06/23/98	Yu	451	528	
	AB	6,290,572 B1	09/18/01	Hofmann	451	5	
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES	TRANSLATION NO
	AK							
	AL							
	AM							
	AN							
	AO							

OTHER PRIOR ART *(Including Author, Title, Date, Pertinent Pages, Etc.)*

	AP	
	AQ	
	AR	

EXAMINER Alvin J. Grant DATE CONSIDERED 11/15/04

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* EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).

Form PT-27/V11/94

FORM PTO-1449 (REV.7-80) — U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

(Use several sheets if necessary)

ATTY. DOCKET NO.	APPLICATION NO.
500200.05	09/910,638
APPLICANT(S)	
Nathan R. Brown	
FILING DATE	GROUP ART UNIT
July 20, 2001	3729

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AQ	5,730,642	3/24/98	Sandhu et al.	451	6	
	AP	5,733,182	3/31/98	Muramatsu et al.	451	289	
	AO	5,766,058	6/16/98	Lee et al.	451	41	
	AN	5,769,692	6/23/98	Pasch et al.	451	41	
	AM	5,769,696	6/23/98	Lee et al.	451	287	
	AL	5,791,973	8/11/98	Nishio	451	41	
	AK	5,888,120	3/30/99	Doran	451	41	
	AJ	5,964,646	10/12/99	Kassir et al.	451	41	
	AI	5,997,385	12/7/99	Nishio	451	56	
	AH	6,019,868	2/1/00	Kimura et al.	156	345	
	AG	6,027,401	2/22/00	Saito et al.	451	398	
	AF	6,036,587	3/14/00	Tolles et al.	451	288	
	AE	6,050,882	4/18/00	Chen	451	41	
	AD	6,074,289	6/13/00	Murakami et al.	451	388	
	AC	6,083,090	7/4/00	Bamba	451	288	
	AB	6,093,085	7/25/00	Yellitz et al.	451	41	
	AA	6,135,858	10/24/00	Takahashi	451	41	

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		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES	TRANSLATION NO
	AR	2,173,639	10/11/96	Canada				

OTHER PRIOR ART *(Including Author, Title, Date, Pertinent Pages, Etc.)*

	AS							
	AT							

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